LM620ULCCP4-0.34x0.23

Mechanical Data

Item		Value
Die Size(mm×mm)		0.340×0.230(包含划片道)
Die Thickness(μm)		635±10
Scribe Line(μm)		40
Bonding PAD Size(μm²)	Top	80×80
Cathode（Top）	Metallization	Al
	Thickness(μm)	1.5 ±0.1
Anode（Bottom）	Metallization	
Die Bonding Requirement（Recommendation）		
Wafer Size(mm)		φ150
Wire Bonding Requirement（Recommendation）		1 Cu Wire, φ20μm

Electrical Characteristics

Parameter	Symbol	Conditions	Min	Typical	Max	Units
Reverse Stand-Off Voltage	V_{RWM}				20	V
Holding Voltage	V_H	$I_T=I_H$		3.0	3.5	V
Holding Current	I_H		35			mA
Reverse Leakage Current	I_R	V_{RWM}=20V,T=25℃			500	nA
Clamping Voltage	V_C	I_{PP}=4A,t_p=8/20μs			8	V
Trigger Voltage	V_T			24		V
Junction Capacitance	C_j	V_R = 0V, f = 1MHz		0.45	0.65	pF

NOTICE
Leiditech reserves the right to make modifications,enhancements,improvements,corrections or other changes without further notice to any product herein. Leiditech does not assume any liability arising out of the application or use of any product described herein.

Shanghai Leiditech Electronic Technology Co., Ltd.
Email: sale1@leiditech.com
Tel : +86- 021 50828806
Fax : +86- 021 50477059